

Preliminary Amendment

Applicant: Michael Bauer, et al.
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Docket No.: I431.170.101/FIN561PCT/US
Title: SEMICONDUCTOR COMPONENT HAVING A STACK OF SEMICONDUCTOR CHIPS AND METHOD FOR PRODUCING THE SAME (as amended)

IN THE ABSTRACT

Please replace the Abstract with the following rewritten paragraph:

SEMICONDUCTOR COMPONENT COMPRISING HAVING A STACK OF SEMICONDUCTOR CHIPS AND METHOD FOR PRODUCING THE SAME

The invention relates to a semiconductor component (14) comprising including a stack (100) of semiconductor chips (1, 2), the semiconductor chips (1, 2) being fixed cohesively one on top of another, is disclosed. The contact areas (5) of the semiconductor chips (1, 2) are led as far as the edges (6) of the semiconductor chips (1, 2) and conductor portions (7) extend at least from an upper edge (8) to a lower edge (9) of the edge sides (10) of the semiconductor chips (1, 2) in order to electrically connect the contact area (5) of the stacked semiconductor chips (1, 2) to one another.

{Figure 1}